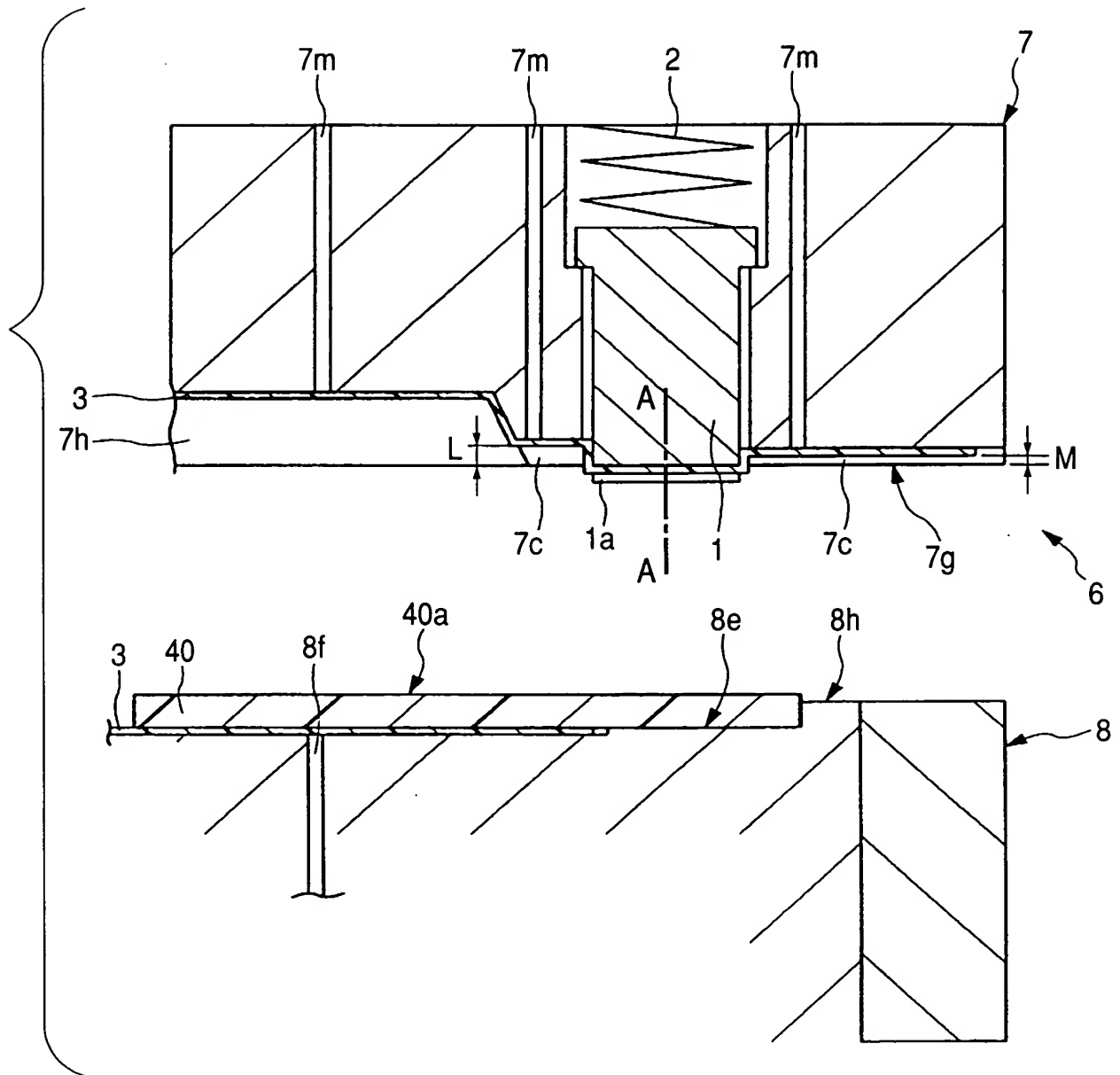


FIG. 1

- | | |
|---|--------------------------------|
| 1: MOVABLE PIN | 7c: AIR VENT |
| 1a: GROOVE | 7g, 8h: MOLD SURFACE |
| 2: SPRING FOR DRIVING
MOVABLE PIN (SPRING) | 7h: COLLECTIVE CAVITY |
| 3: FILM | 7m, 8f: SUCTION HOLE |
| 6: FORMING MOLD | 8: LOWER MOLD (SECOND MOLD) |
| 7: UPPER MOLD (FIRST MOLD) | 40: MULTI-CAVITY BOARD (BOARD) |

FIG. 2

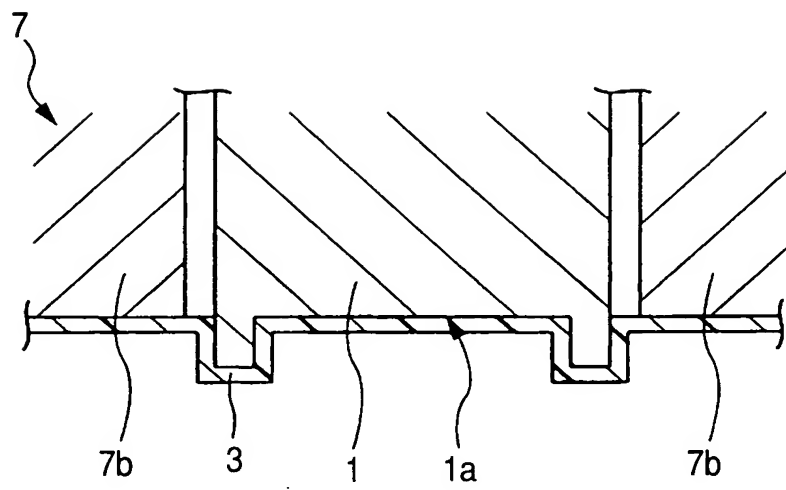
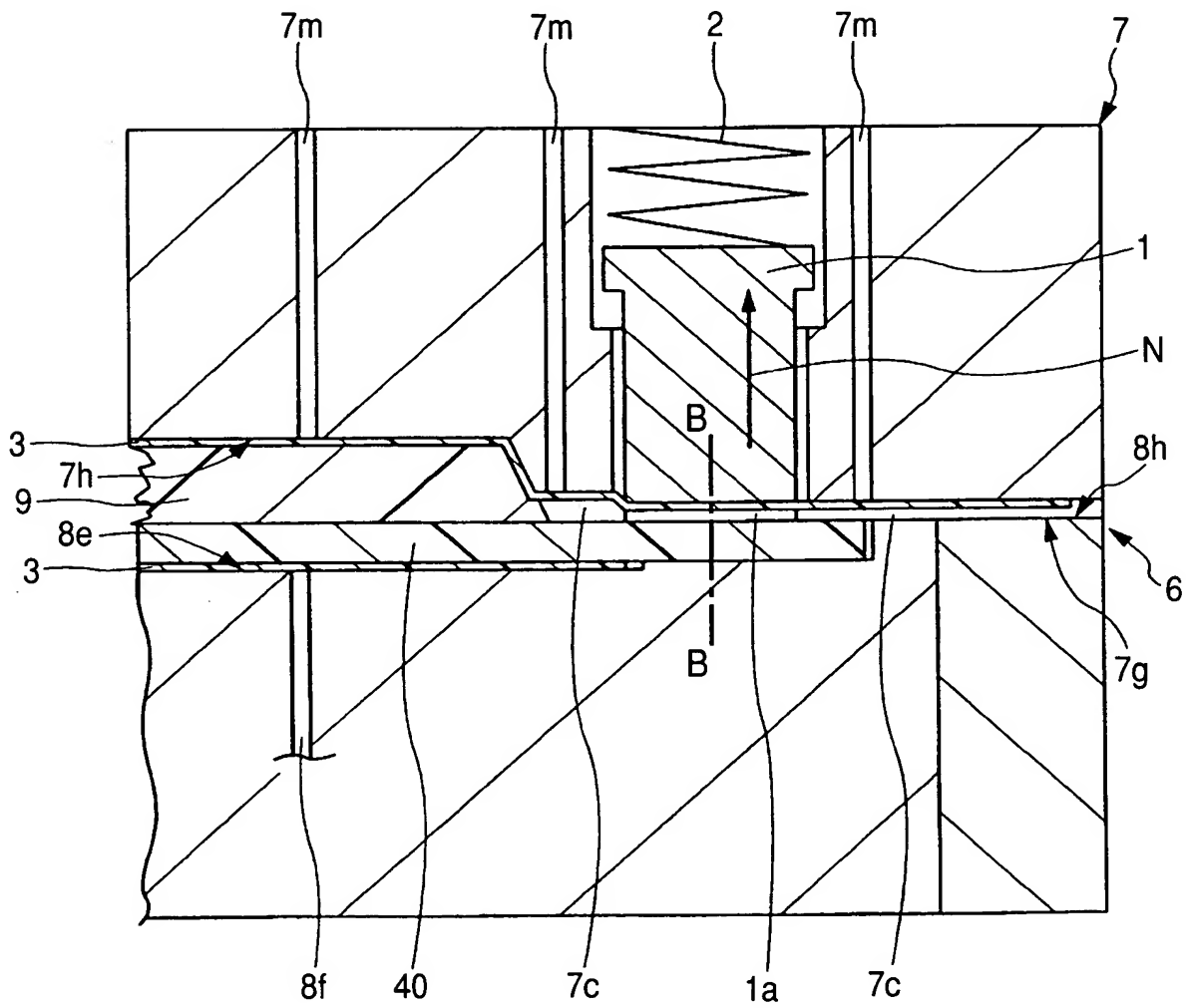


FIG. 3



9 : SEALING RESIN

FIG. 4

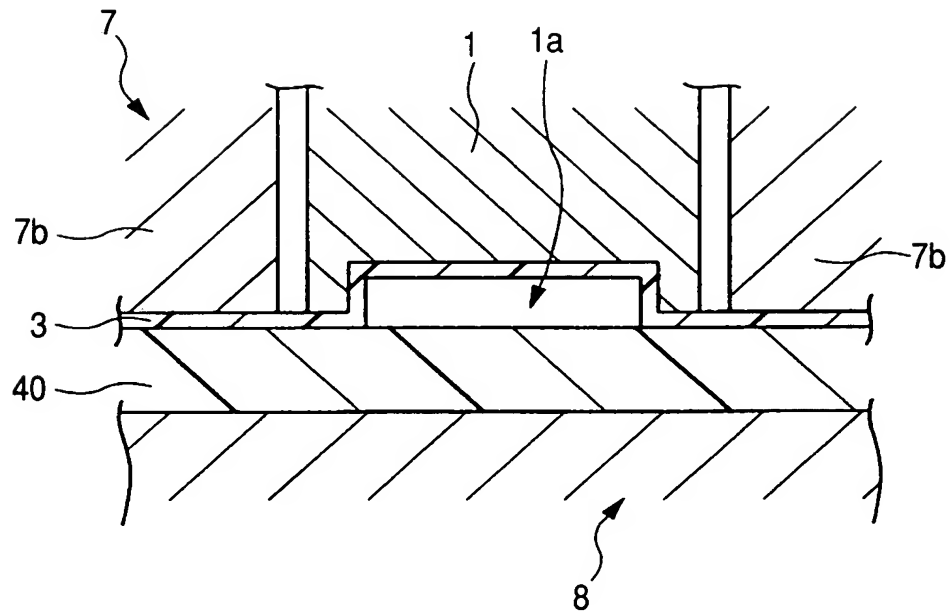
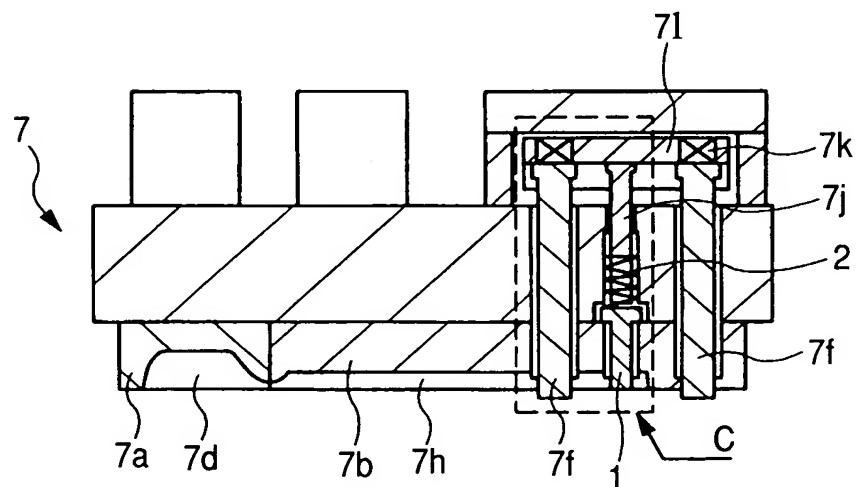


FIG. 5



7j : RAMMER FOR MOVABLE PIN (PUSHER ROD)

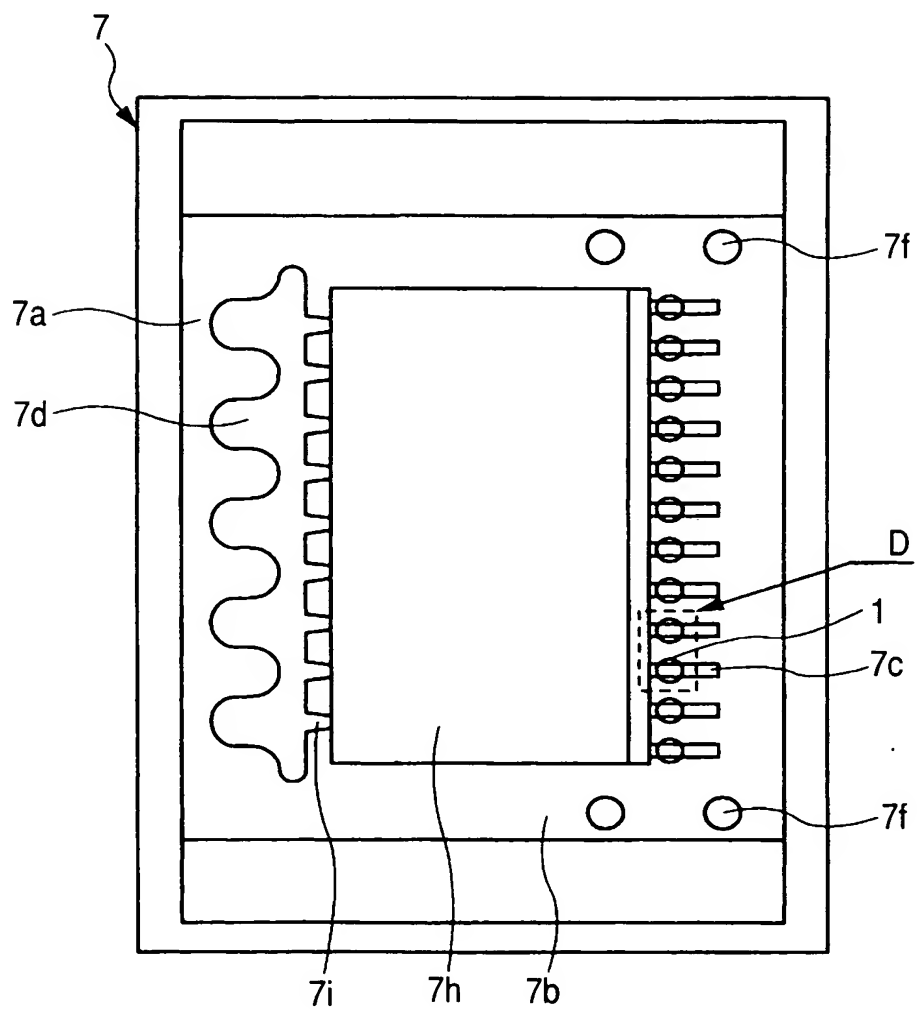
FIG. 6

FIG. 7

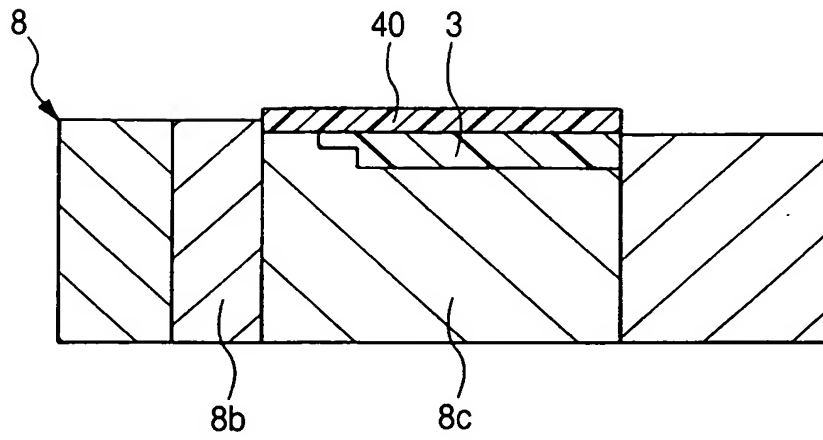


FIG. 8

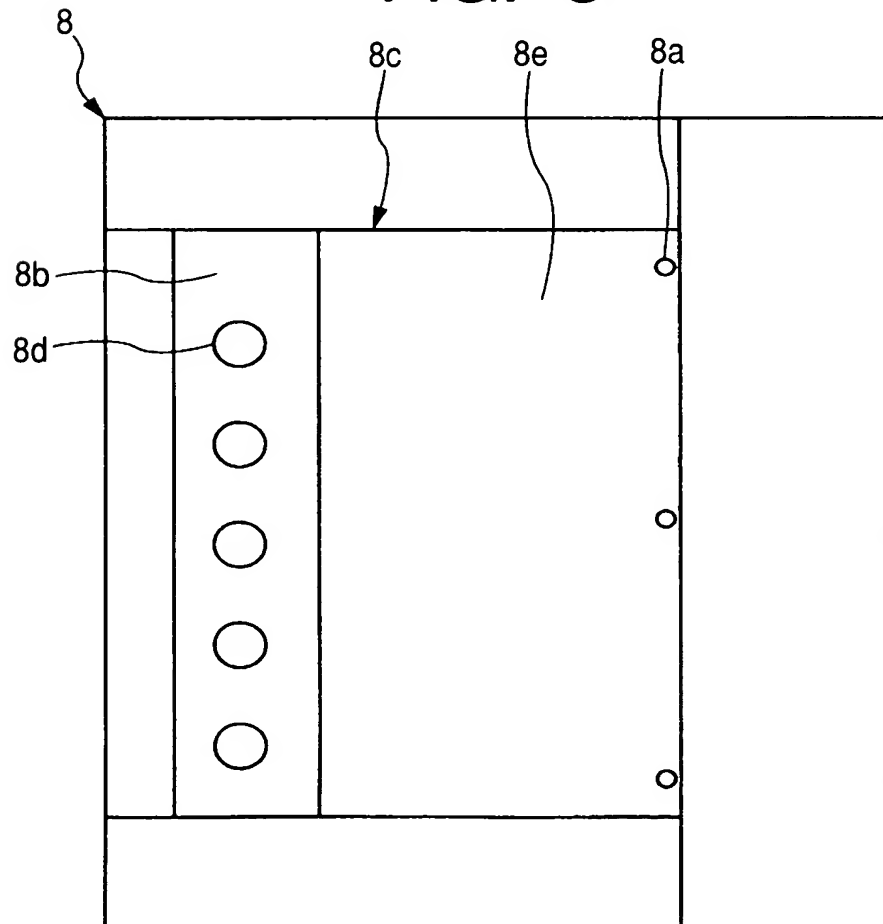


FIG. 9

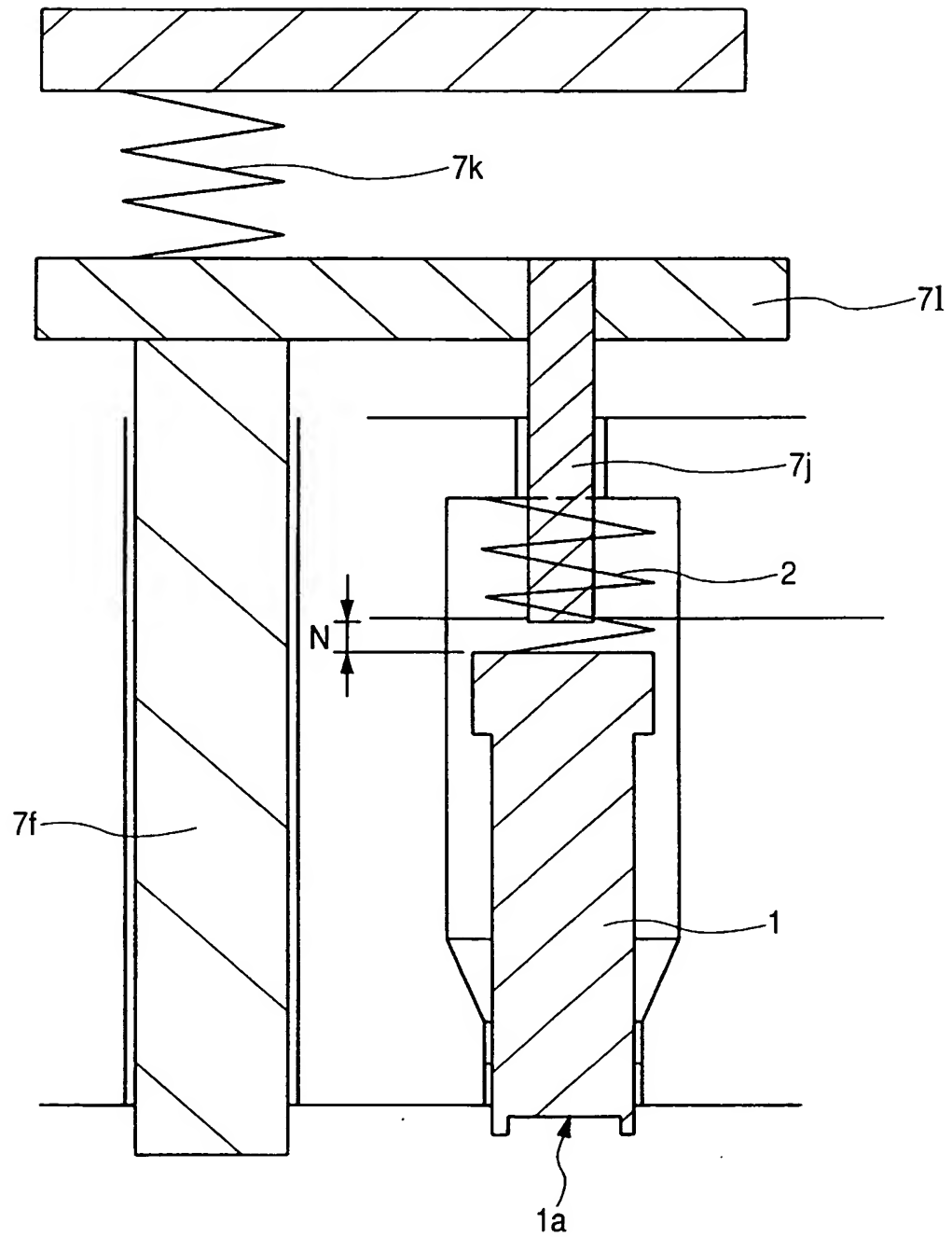


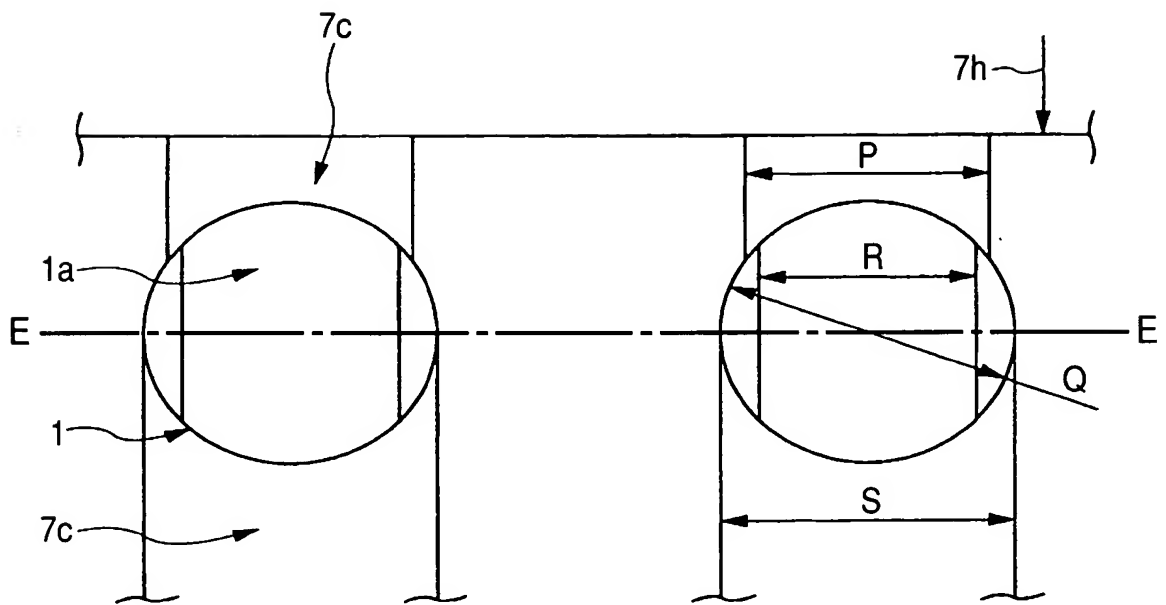
FIG. 10

FIG. 11

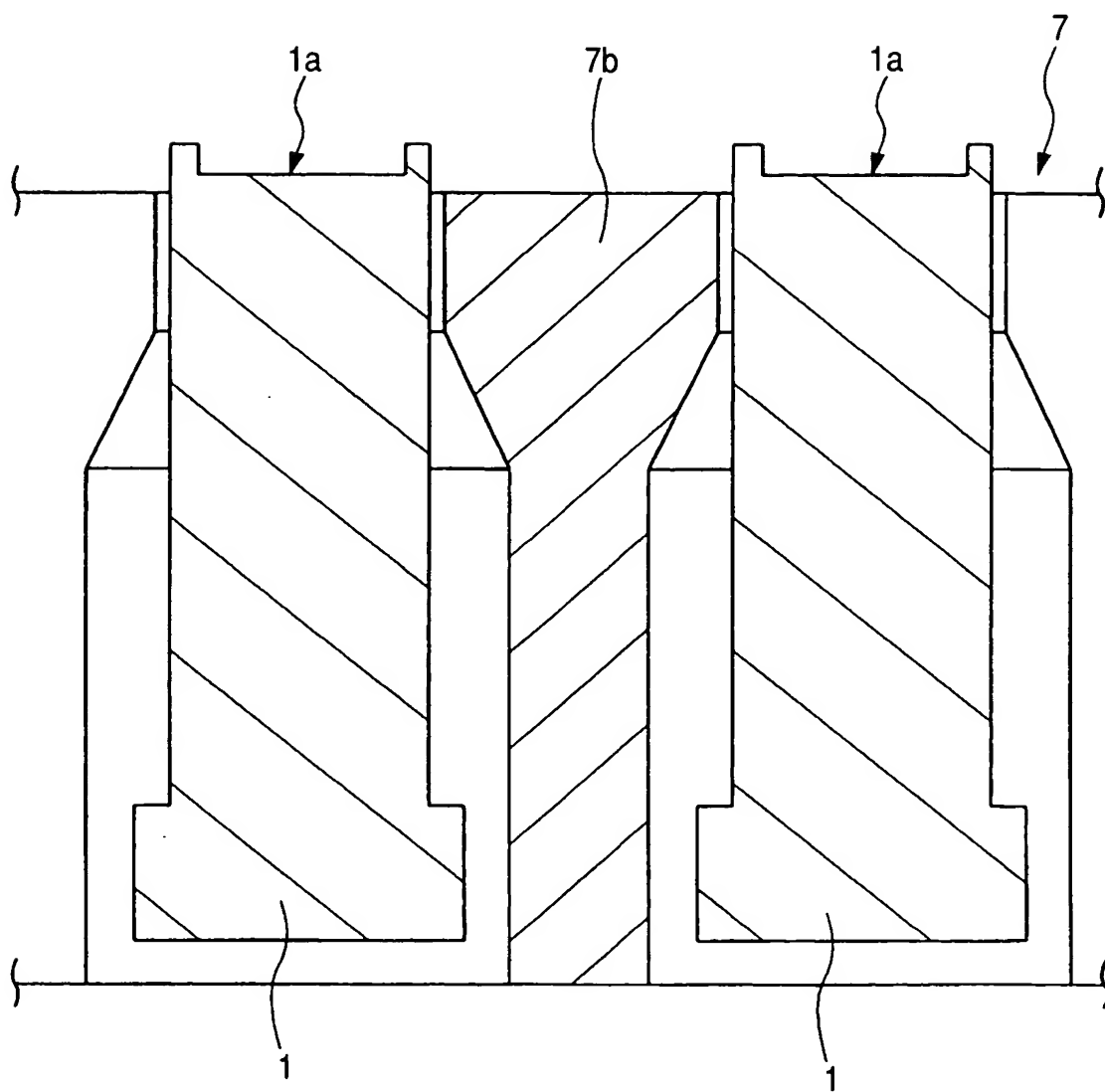


FIG. 12

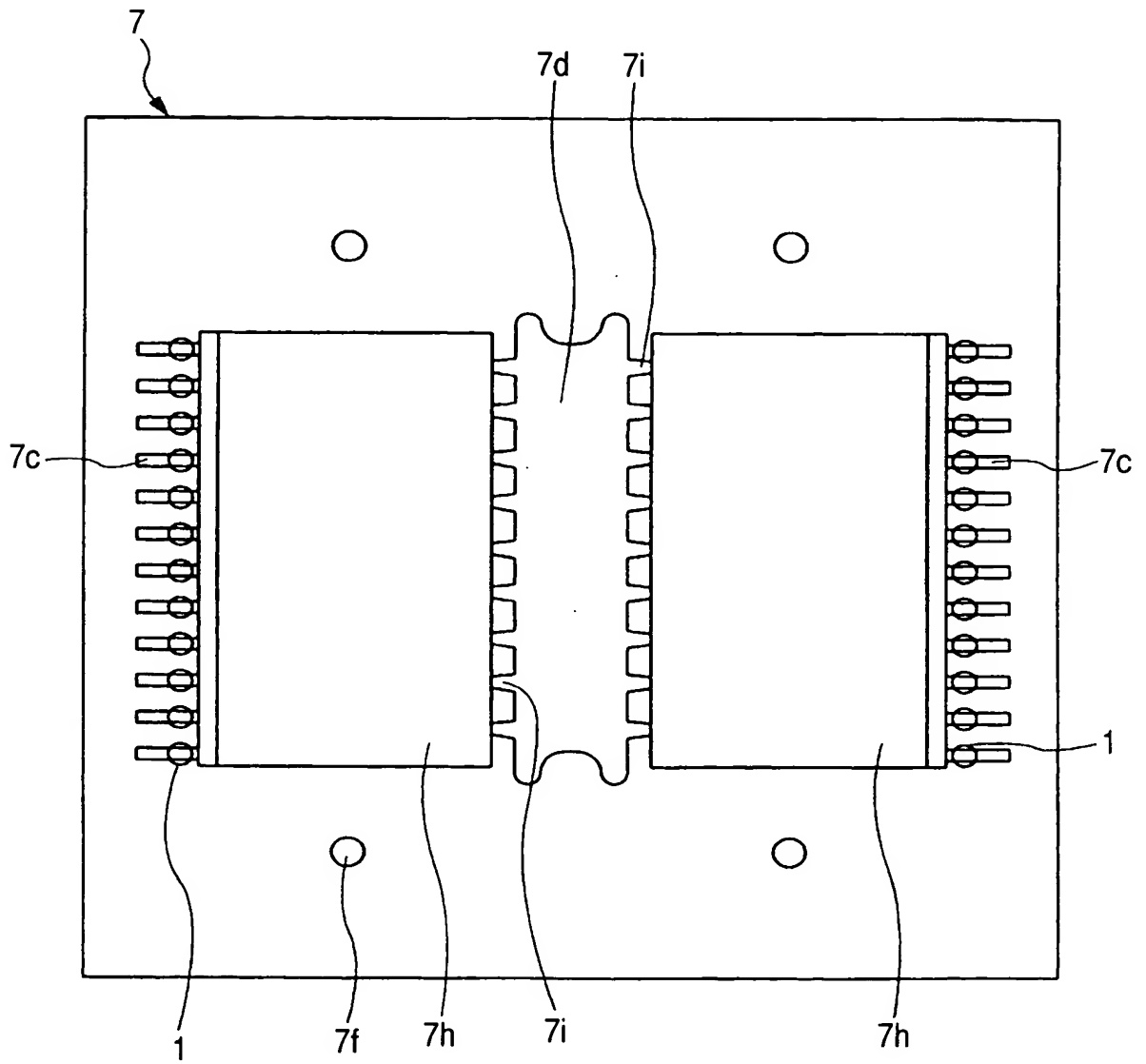


FIG. 13

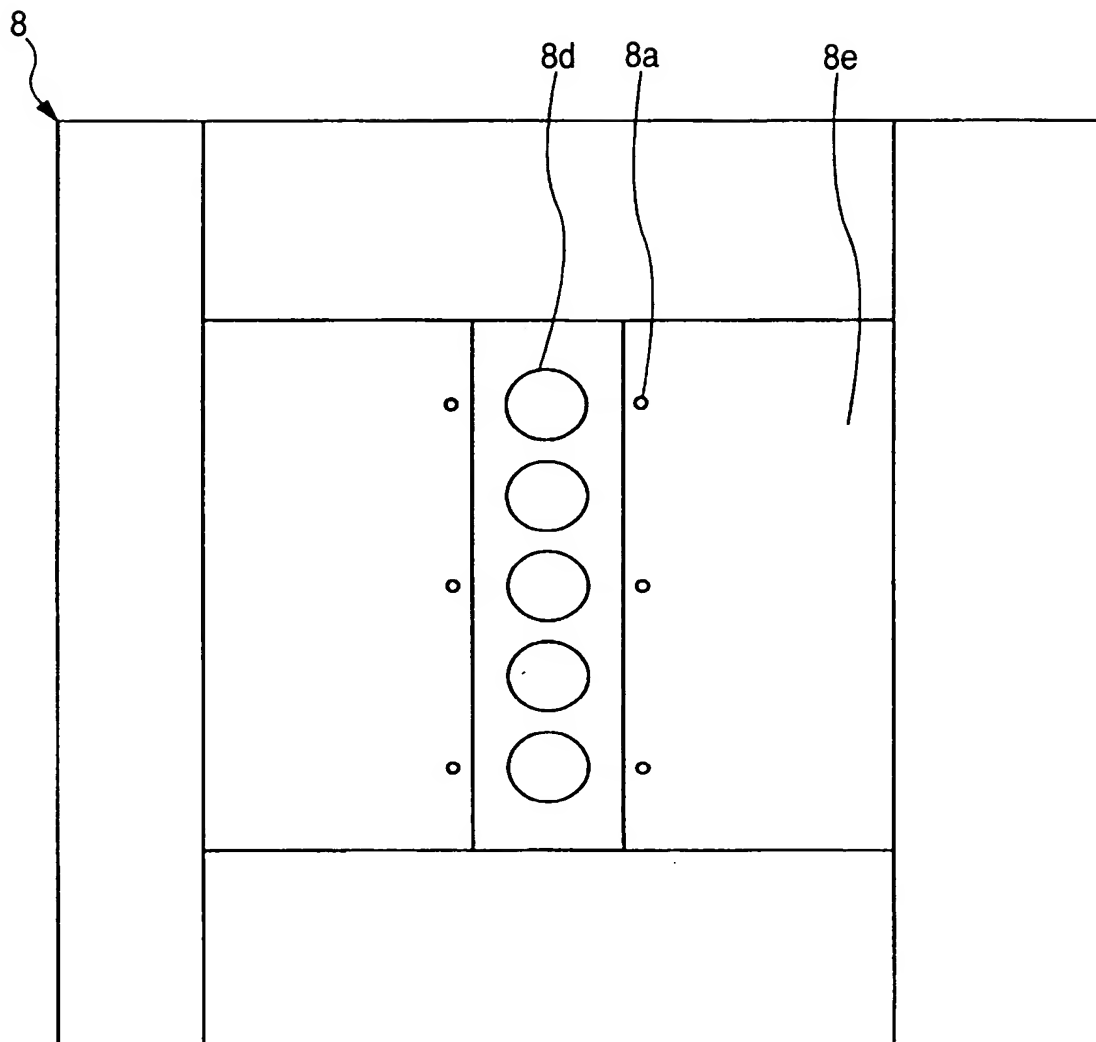
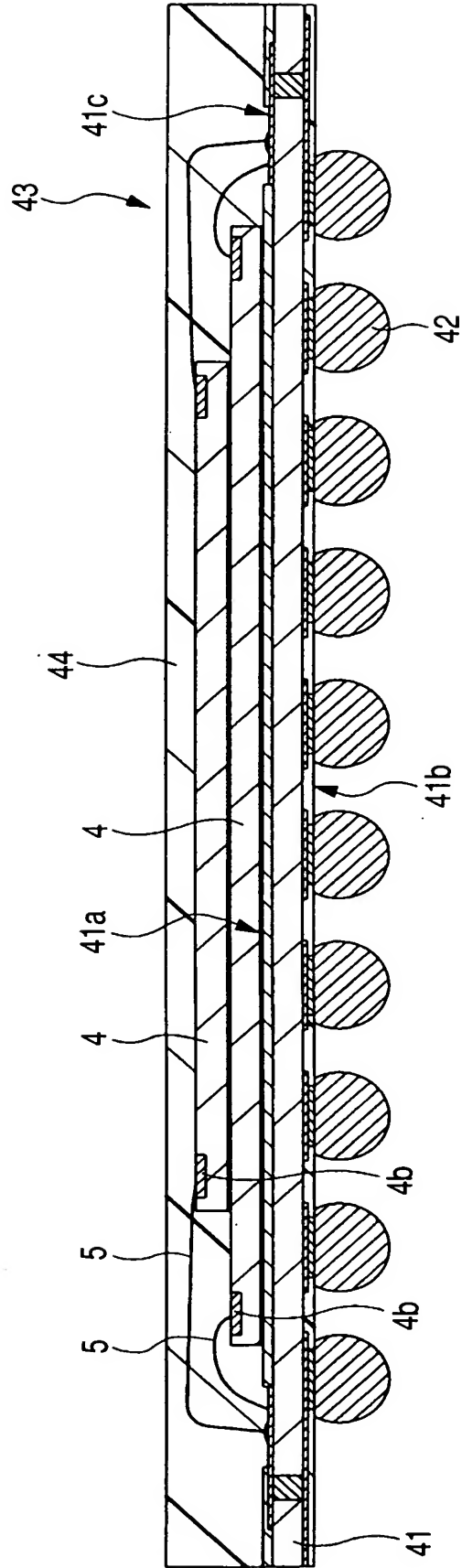
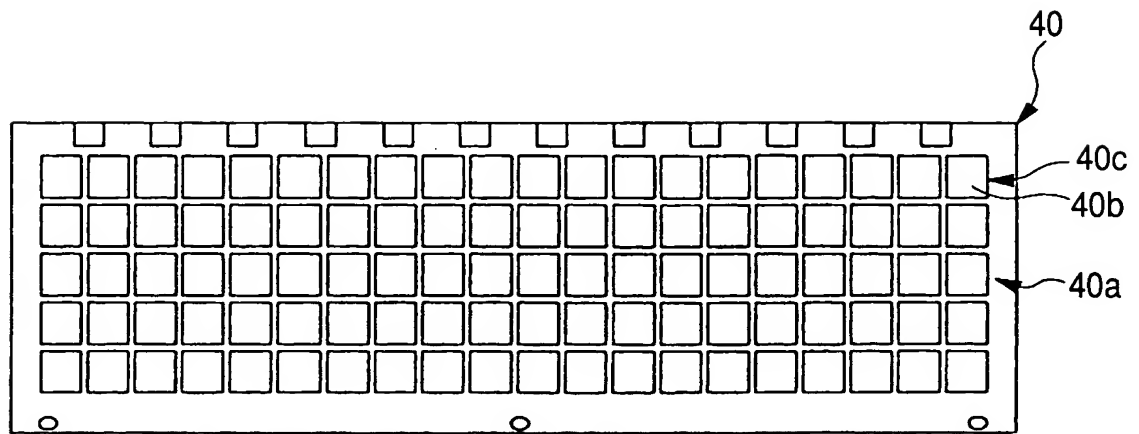


FIG. 14



- 4 : SEMICONDUCTOR CHIP
- 41 : PRINTED WIRING BOARD (BOARD)
- 43 : CSP (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

FIG. 15

40b : CHIP MOUNTING AREA
40c : DEVICE AREA (DEVICE FORMING AREA)

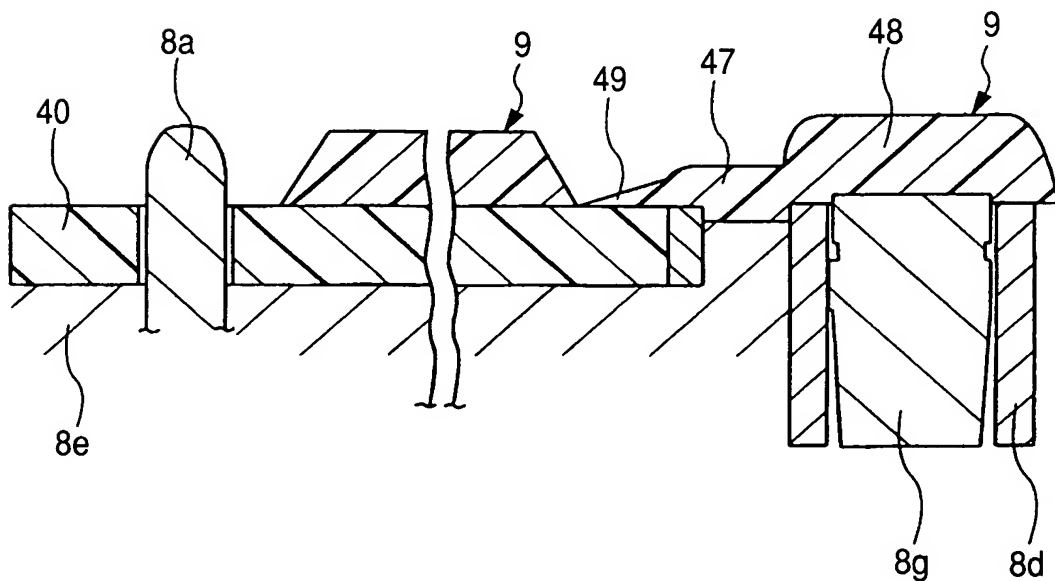
FIG. 16

FIG. 17

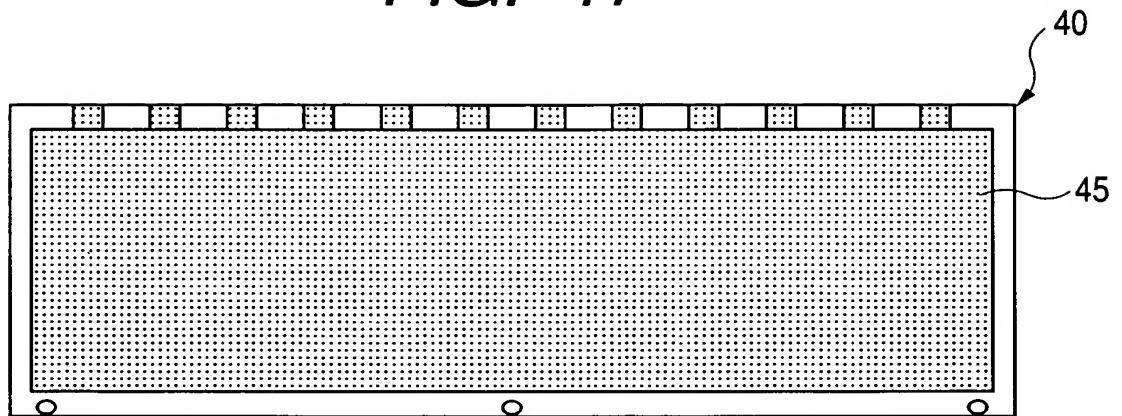


FIG. 18

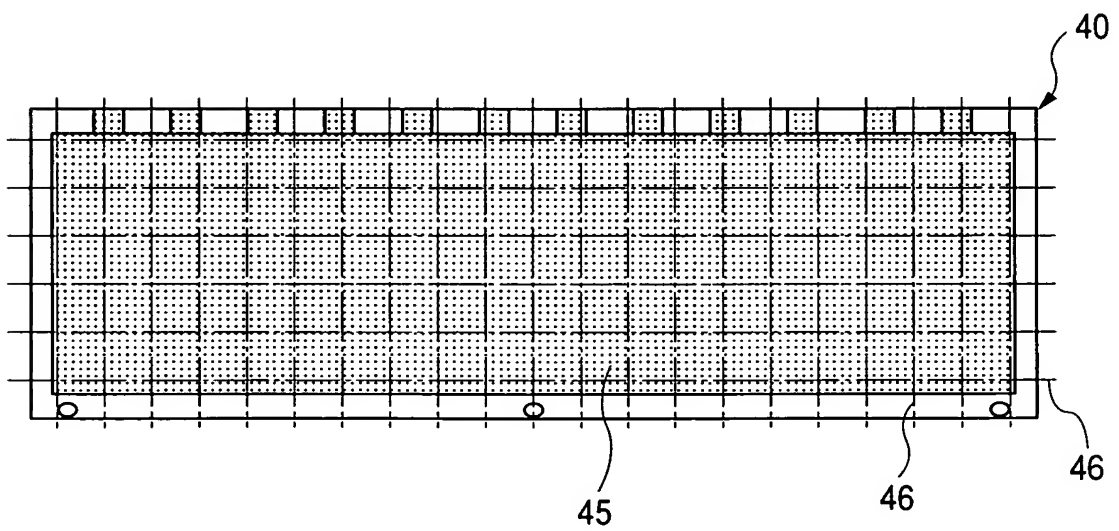


FIG. 19

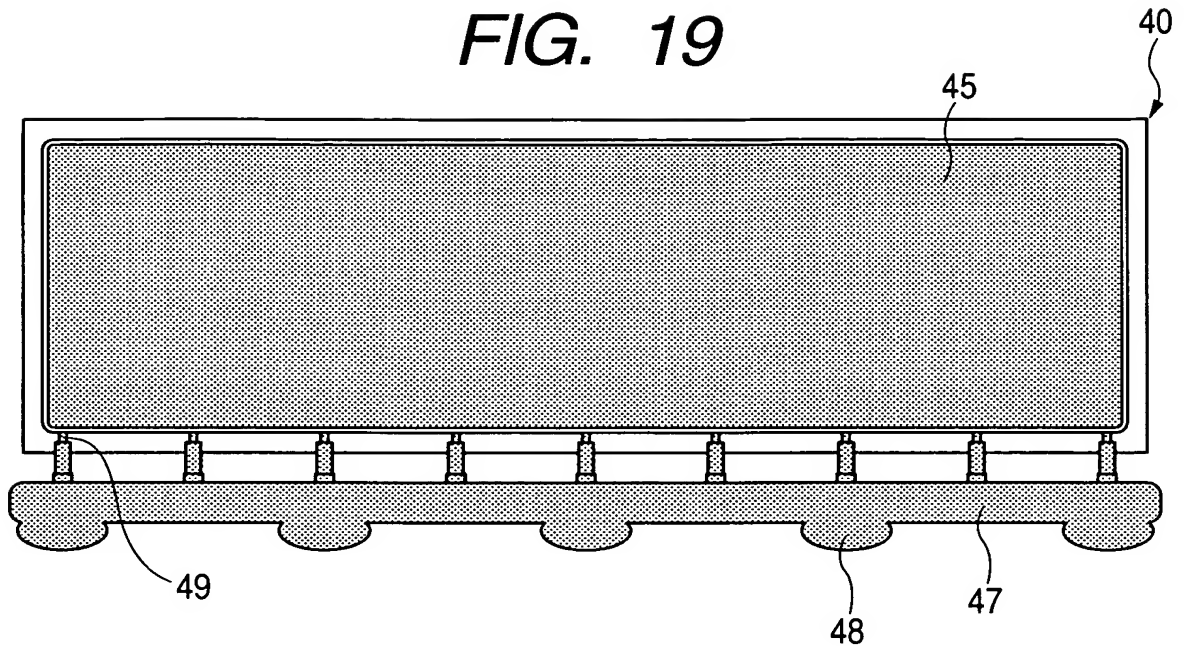


FIG. 20

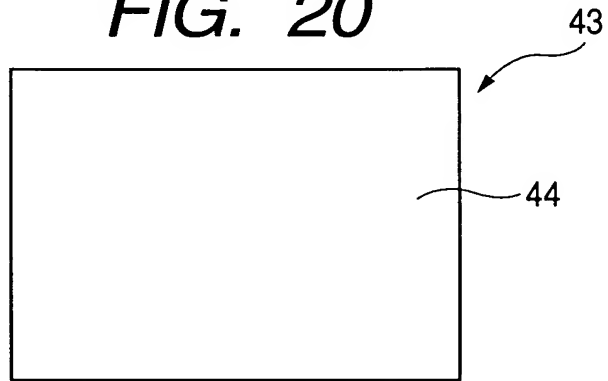


FIG. 21

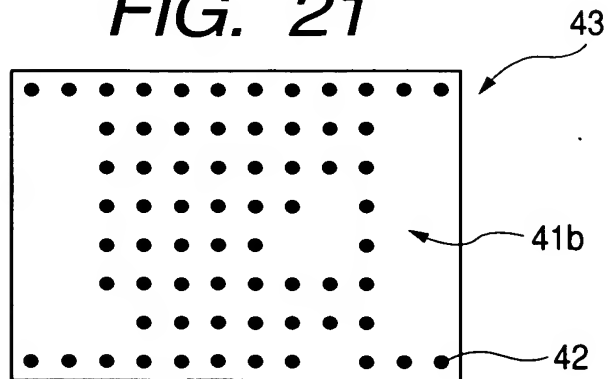




FIG. 23



FIG. 24

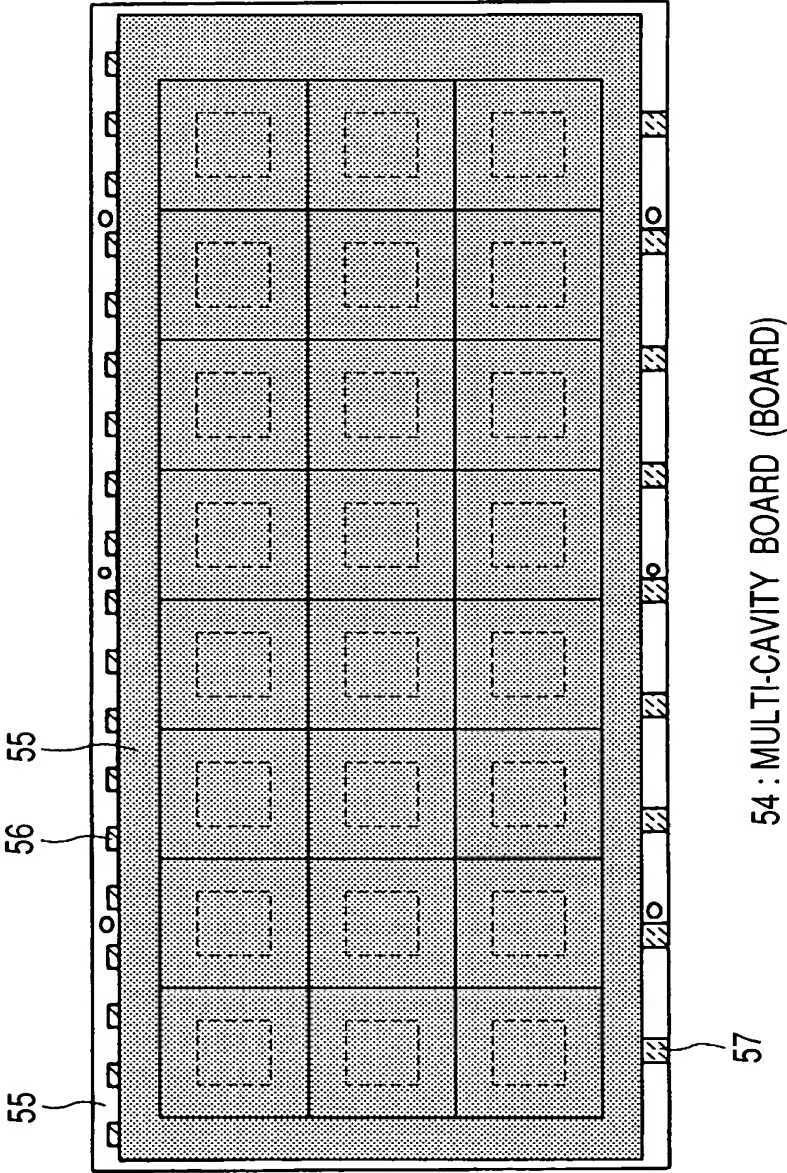


FIG. 25

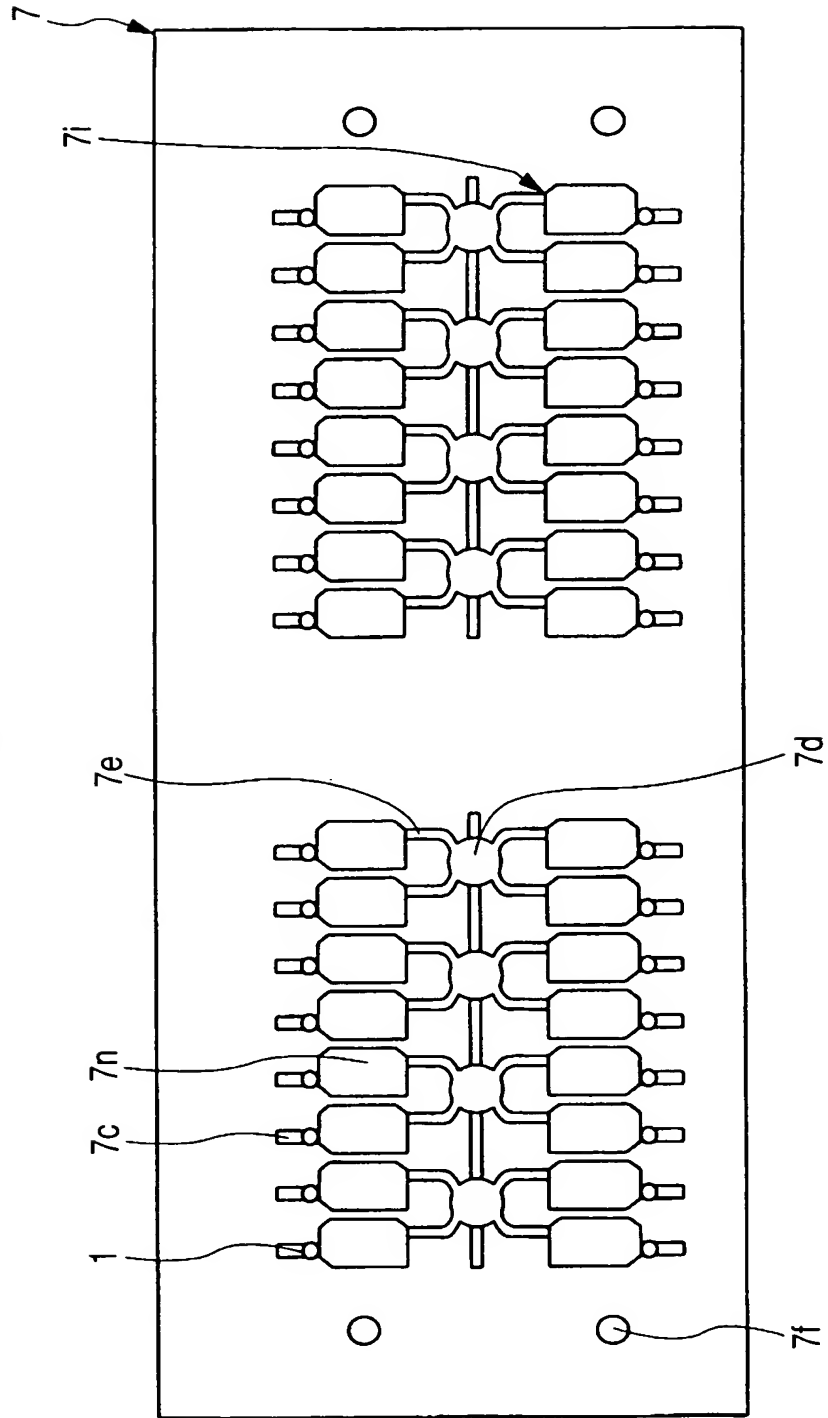


FIG. 26

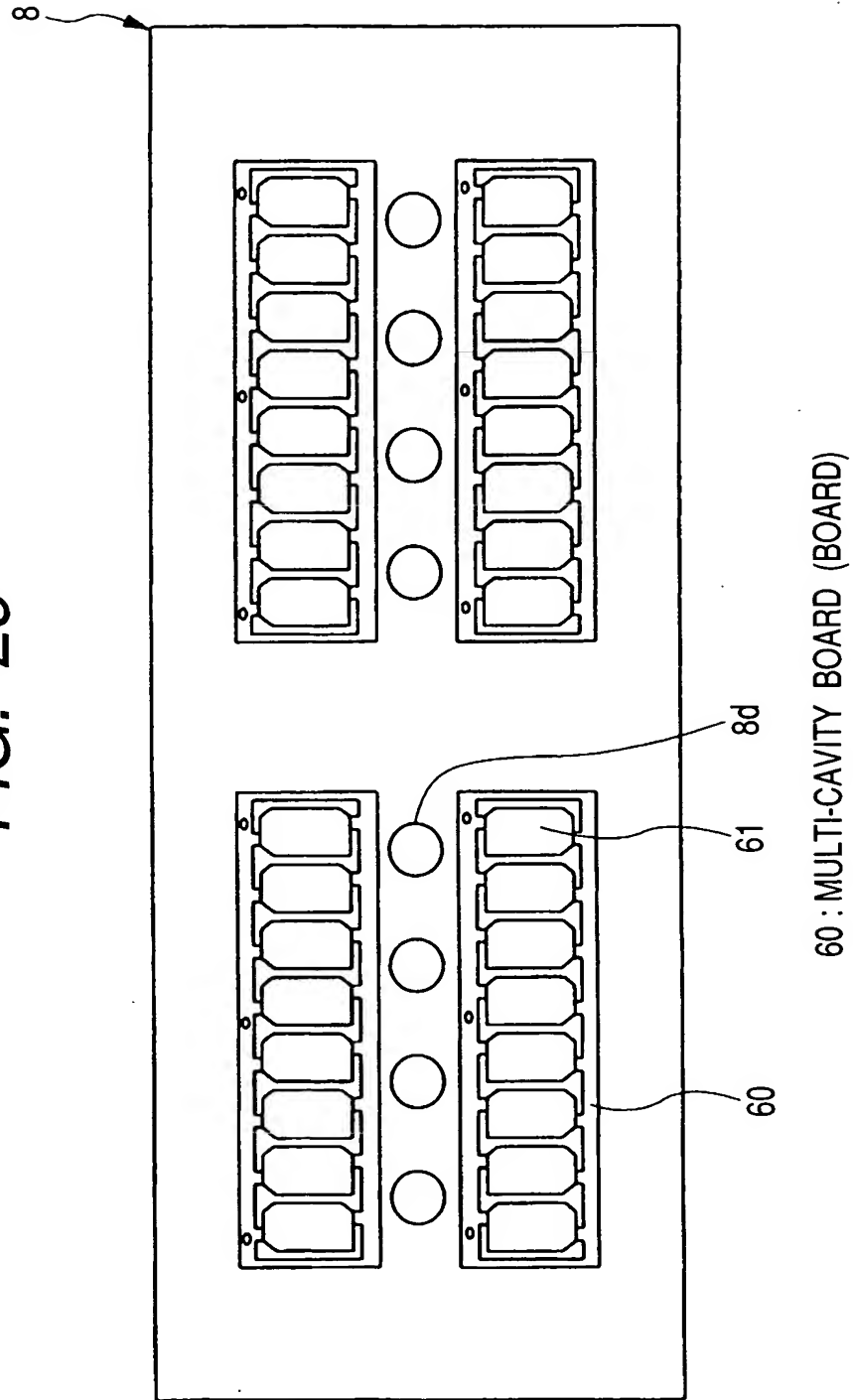


FIG. 27

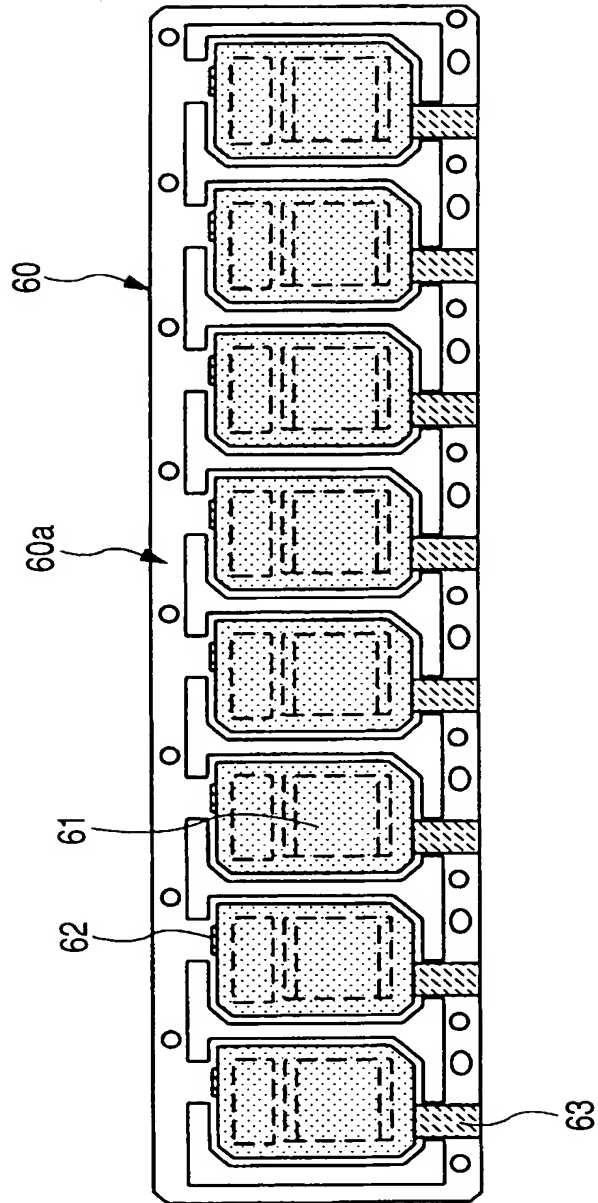
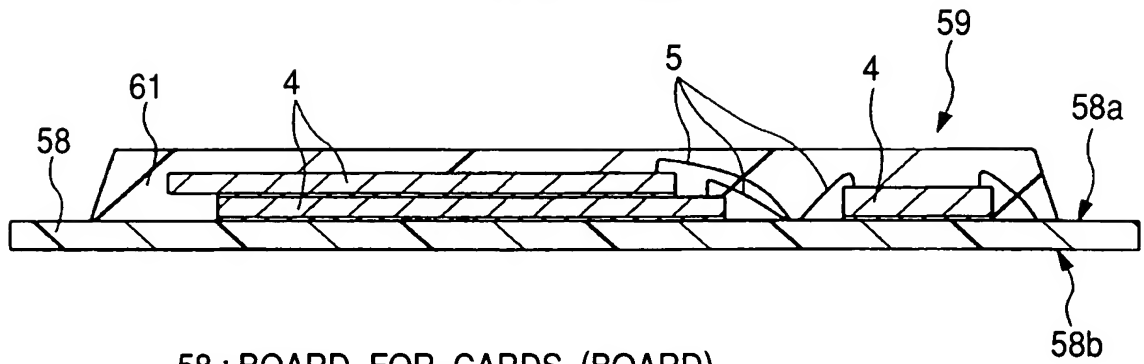


FIG. 28



58 : BOARD FOR CARDS (BOARD)
 59 : CARD-TYPE PACKAGE
 (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

FIG. 29

